18**∏** 1C

17 2C

16 1 3C

15 **∏** 4C

14 🛮 5C

12 7C

11 1 8C

10 **∏** COM

13 **∏** 6C

N PACKAGE (TOP VIEW)

1B

2B **∏** 2

3B [ 3

48 [

5В П

6В [

7B

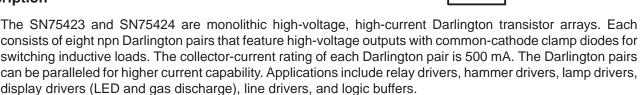
GND [

8B **∏** 

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- 500-mA Rated Collector Current (Single Output)
- High-Voltage Outputs . . . 100 V
- Output Clamp Diodes
- Inputs Compatible With Various Types of Logic
- Relay Driver Applications
- Compatible With ULN2800A Series
- Packaged in Plastic (N) DIPs

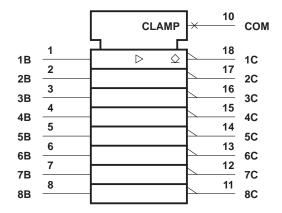
### description



The SN75423 has a 2700- $\Omega$  series base resistor for each Darlington pair for operation directly with TTL or 5-V CMOS. The SN75424 has a 10.5-k $\Omega$  series base resistor to allow operation directly with CMOS or PMOS that use supply voltages of 6 to 15 V.

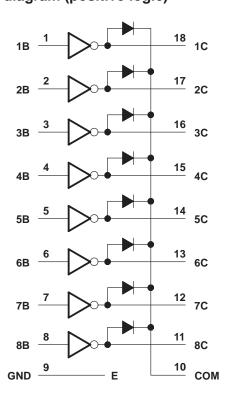
The SN75423 and SN75424 are designed for operation from 0°C to 85°C.

## logic symbol†



† This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.

## logic diagram (positive logic)



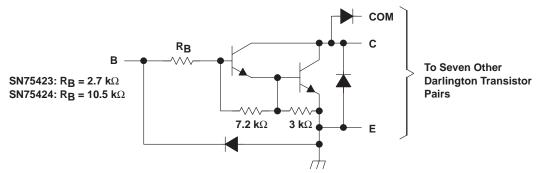


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### schematic (each Darlington pair)



All resistor values shown are nominal.

## absolute maximum ratings at 25°C free-air temperature (unless otherwise noted)

Collector-emitter voltage, V <sub>CE</sub>	100 V
Input voltage, V <sub>I</sub> (see Note 1)	
Continuous collector current	500 mA
Output clamp diode current, I <sub>OK</sub>	500 mA
Total substrate-terminal current	2.5 A
Continuous total power dissipation at or below 25°C free air temperature	1150 mW
Operating free-air temperature range, T <sub>A</sub>	)°C to 85°C
Storage temperature range, T <sub>stq</sub> 65°	C to 150°C
Lead temperature 1,6 mm (1/16 inch) from case for 10 seconds	260°C

NOTE 1: All voltage values are with respect to the emitter/substrate, terminal 9.



# electrical characteristics, $T_A = 25^{\circ}C$ (unless otherwise noted)

PARAMETER		TEST TEST CONDITIONS		SN75423			SN75424			UNIT		
		FIGURE	TEST CONDITIONS		MIN	TYP	MAX	MIN	TYP	MAX	UNII	
	On-state input voltage		V <sub>CE</sub> = 2 V	I <sub>C</sub> = 125 mA						5	5 6 7	
V <sub>I(on)</sub>				I <sub>C</sub> = 200 mA			2.4			6		
		5		I <sub>C</sub> = 250 mA			2.7					
		5		I <sub>C</sub> = 275 mA						7		
				$I_C = 300 \text{ mA}$			3					
				$I_C = 350 \text{ mA}$						8		
	0 "		$I_I = 250 \mu A$ ,	$I_C = 100 \text{ mA}$		0.9	1.1		0.9	1.1	V	
VCE(sat)	Collector-emitter saturation voltage	6	$I_I = 350 \mu A$ ,	$I_C = 200 \text{ mA}$		1	1.3		1	1.3		
			$I_I = 500 \mu A$ ,	$I_C = 350 \text{ mA}$		1.2	1.6		1.2	1.6		
VF	Clamp-diode forward voltage	8	I <sub>F</sub> = 350 mA			1.7	2		1.7	2	V	
	Collector cutoff current		1	$V_{CE} = 100 \text{ V},$	I <sub>I</sub> = 0			100			100	
ICEX			2	V <sub>CE</sub> = 100 V, T <sub>A</sub> = 70°C	V <sub>I</sub> = 1 V,						500	μΑ
I(off)	Off-state input current	3	V <sub>CE</sub> = 100 V, T <sub>A</sub> = 70°C	I <sub>C</sub> = 500 μA,	50	65		50	65		μΑ	
II(on)	Input current		V <sub>I</sub> = 3.85 V			0.93	1.35					
		4	V <sub>I</sub> = 5 V						0.35	0.5	mA	
			V <sub>I</sub> = 12 V						1	1.45		
I <sub>R</sub>	Clamp-diode reverse current	7	V <sub>R</sub> = 100 V			·	50	·		50	μΑ	
Ci	Input capacitance		$V_I = 0$ ,	f = 1 MHz		15	30		15	30	pF	

# switching characteristics, $T_A = 25^{\circ}C$ free-air temperature

	PARAMETER	TEST CONDITIONS	MIN TYP MAX	UNIT
tPLH	Propagation delay time, low-to-high-level output	$V_S = 50 \text{ V}, \qquad R_L = 163 \ \Omega, \qquad C_L = 15 \text{ pF},$ See Figure 9	130	ns
tPHL	Propagation delay time, high-to-low-level output	$V_S = 50 \text{ V}, \qquad R_L = 163 \ \Omega, \qquad C_L = 15 \text{ pF},$ See Figure 9	20	ns
Vон	High-level output voltage after switching	$V_S = 60 \text{ V}$ , $I_O \approx 300 \text{ mA}$ , See Figure 10	V <sub>S</sub> -20	mV

### PARAMETER MEASUREMENT INFORMATION

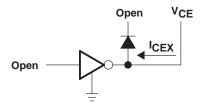


Figure 1. I<sub>CEX</sub>

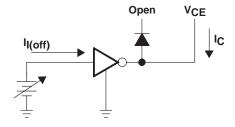


Figure 3. I<sub>I(off)</sub>

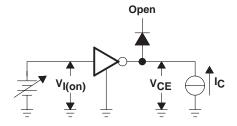


Figure 5. V<sub>I(on)</sub>

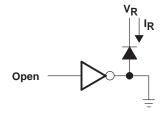


Figure 7. I<sub>R</sub>

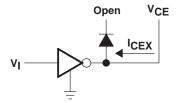


Figure 2. I<sub>CEX</sub>

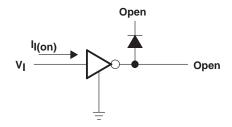


Figure 4. I<sub>I(on)</sub>

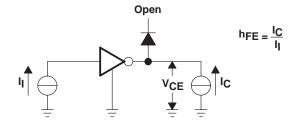


Figure 6. hFE, VCE(sat)

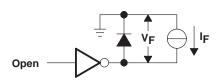
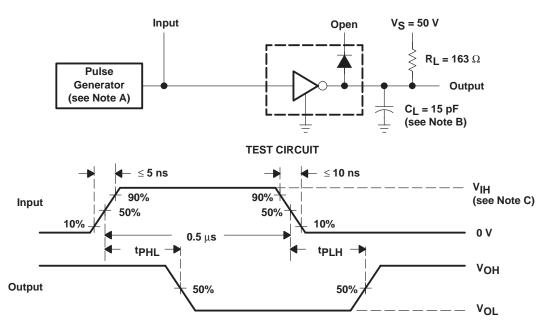


Figure 8. V<sub>F</sub>

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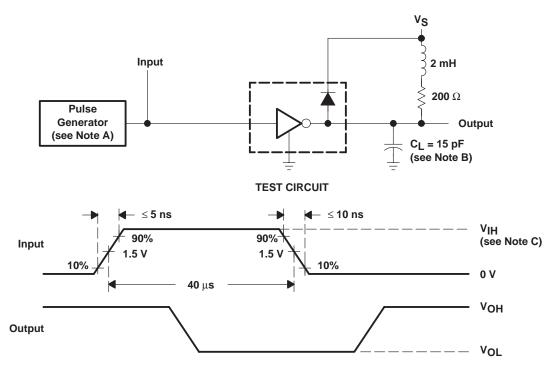
### PARAMETER MEASUREMENT INFORMATION



NOTES: A. The pulse generator has the following characteristics: PRR = 12.5 kHz,  $Z_O$  = 50  $\Omega$ .

- B. C<sub>L</sub> includes probe and jig capacitance.
- C. For testing the SN75423,  $V_{IH} = 3 \text{ V}$ ; for the SN75424,  $V_{IH} = 8 \text{ V}$ .

Figure 9. Propogation Delay Test Circuit and Voltage Waveforms



NOTES: A. The pulse generator has the following characteristics: PRR = 12.5 kHz,  $Z_0$  = 50  $\Omega$ .

- B. C<sub>L</sub> includes probe and jig capacitance.
- C. For testing the SN75423,  $V_{IH} = 3 V$ ; for the SN75424,  $V_{IH} = 8 V$ .

Figure 10. Latch-Up Test Circuit and Voltage Waveforms





### PACKAGE OPTION ADDENDUM

30-Mar-2005

#### **PACKAGING INFORMATION**

Orderable Device	Status <sup>(1)</sup>	Package Type	Package Drawing	Pins Package Qty	Eco Plan <sup>(2)</sup>	Lead/Ball Finish	MSL Peak Temp <sup>(3)</sup>
SN75423N	OBSOLETE	PDIP	N	18	TBD	Call TI	Call TI
SN75423N-90	OBSOLETE	PDIP	N	18	TBD	Call TI	Call TI

<sup>(1)</sup> The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in

a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

**OBSOLETE:** TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS) or Green (RoHS & no Sb/Br) - please check <a href="http://www.ti.com/productcontent">http://www.ti.com/productcontent</a> for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

**Pb-Free** (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

(3) MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

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